

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Shigun Oh</td><td>04/20/2005</td></tr><tr><td>Teruhiko Fujiwara</td><td>04/20/2005</td></tr><tr><td>Yasubumi Kikuchi</td><td>04/20/2005</td></tr><tr><td>Takashi Yambe</td><td>04/20/2005</td></tr></tbody></table>	Name	Execution Date	Shigun Oh	04/20/2005	Teruhiko Fujiwara	04/20/2005	Yasubumi Kikuchi	04/20/2005	Takashi Yambe	04/20/2005	
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Takashi Yambe	04/20/2005										
RECEIVING PARTY DATA											
Name:	NEC TOKIN Corporation										
Street Address:	7-1, Koriyama 6-chome										
Internal Address:	Taihaku-ku, Sendai-shi										
City:	Miyaki										
State/Country:	JAPAN										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>10528305</td></tr></tbody></table>	Property Type	Number	Application Number:	10528305							
Property Type	Number										
Application Number:	10528305										
CORRESPONDENCE DATA											
Fax Number:	(201)239-0734										
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Total Attachments: 3											
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PATENT
REEL: 016286 FRAME: 0455

ASSIGNMENT

This assignment, by SHIGUN OH, TERUHIKO FUJIWARA,
YASUBUMI KIKUCHI and TAKASHI YAMBE,
(hereinafter collectively the "assignor"), witnesseth:

WHEREAS, the assignor is the sole owner of an invention entitled
**Method of manufacturing a bond magnet and method of manufacturing
a magnetic device including a bond magnet**
as set forth in an application for Letters Patent of the United States accorded serial
number 10/528,305 and filed on 03/17/2005, which corresponds to International
Application No. PCT/JP03/011970 filed on 09/19/2003; and

WHEREAS, NEC TOKIN Corporation,
7-1, Koriyama 6-chome, Taihaku-ku, Sendai-shi, Miyagi, Japan
(hereinafter the "assignee"), has agreed to accept an interest in any and all income,
from sales, licenses, or otherwise, generated from said invention and said patent in
exchange for its fees for prosecution of the application;

NOW, THEREFORE, for valuable consideration, receipt of which is hereby
acknowledged, the assignor hereby sells, assigns, transfers, and sets over, unto the
assignee, its successors, legal representatives, and assigns, the entire right, title, and
interest in and to the abovementioned inventions, application, and any and all Letters
Patent or Patents in the United States of America and all foreign countries which may
be granted therefor and thereon, and in and to any and all divisions, continuations,
and continuations-in-part of said application, or reissues or extensions thereof, and to
invoke and claim for any application for patent or other form of protection for said
invention(s) filed by it or them, the benefit of all rights under the International
Convention for the Protection of Industrial Property, as amended, or by any

convention which may henceforth be substituted for it, the same to be held and enjoyed by the assignee, for its own use and behoof and that of its successors, legal representatives, and assigns, to the full end of the term or terms for which Letters Patent or Patents may be granted, as fully and entirely as the same would have been held and enjoyed by the assignor had this transfer not been made.

AND for the same consideration, the said assignor hereby covenants and agrees to and with the said assignee, its successors, legal representatives, and assigns, that, at the time of execution and delivery of these presents, the said assignor is the sole and lawful owner of the entire right, title, and interest in and to the said invention(s) and the application(s) and/or patent(s) above mentioned, and that the same are unencumbered and that the said assignor have good and full right and lawful authority to sell and convey the same in the manner herein set forth.

AND for the same consideration, the said assignor hereby covenants and agrees to and with the said assignee, its successors, legal representatives, and assigns, whenever counsel of any of the same shall advise that any proceeding in connection with said inventions or said application for Letters Patent, or any proceeding in connection with Letters Patent for said inventions in any country, including interference proceedings, is lawful and desirable, or that any division, continuation, or continuation-in-part of any application for Letters Patent, or any reissue or extension of any Letters Patent for said inventions in any country to be obtained thereon is lawful and desirable, that they shall sign all papers and documents, take all lawful oaths, and do all acts necessary or required to be done for the procurement, maintenance, enforcement, and defense of Letters Patent for said inventions, without charge to the assignee, its successors, legal representatives, and assigns, but at the cost and expense of the assignee, its successors, legal representatives, and assigns.

AND the said assignor hereby requests the Commissioner of Patents to issue said Letters Patent of the United States to the said assignee as the assignee of said

invention(s) and the Letters Patent to be issued thereon for the sole use and behoof of the assignee, its successors, legal representatives, and assigns.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in any country for any purpose and more particularly in proof of the right of the said assignee or nominee to claim the aforesaid benefits provided under the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

I covenant with said assignee, its successors, assigns and legal representatives, that the rights and property herein conveyed are free and clear of any encumbrance, and that we have full right to convey the same as herein expressed.

Date: 04/20/2005 Signature of Assignor: Shigun Oh
SHIGUN OH

Date: 04/20/2005 Signature of Assignor: Teruhiko Fujiwara
TERUHIKO FUJIWARA

Date: 04/20/2005 Signature of Assignor: Yasubumi Kikuchi
YASUBUMI KIKUCHI

Date: 04/20/2005 Signature of Assignor: Takashi Yambe
TAKASHI YAMBE

Date: _____ Signature of Assignor: _____

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